
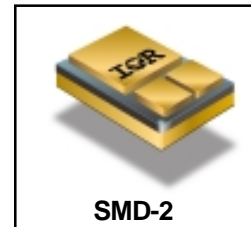


**RADIATION HARDENED
 POWER MOSFET
 SURFACE MOUNT (SMD-2)**

**IRHNA597260
 200V, P-CHANNEL
 **TECHNOLOGY****

Product Summary

Part Number	Radiation Level	RDS(on)	ID
IRHNA597260	100K Rads (Si)	0.102Ω	-35.5A
IRHNA593260	300K Rads (Si)	0.102Ω	-35.5A



International Rectifier's R5™ technology provides high performance power MOSFETs for space applications. These devices have been characterized for Single Event Effects (SEE) with useful performance up to an LET of 80 (MeV/(mg/cm²)). The combination of low RDS(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

Features:

- Single Event Effect (SEE) Hardened
- Ultra Low RDS(on)
- Low Total Gate Charge
- Proton Tolerant
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Ceramic Package
- Light Weight

Absolute Maximum Ratings

Pre-Irradiation

	Parameter		Units
ID @ VGS = -12V, TC = 25°C	Continuous Drain Current	-35.5	A
ID @ VGS = -12V, TC = 100°C	Continuous Drain Current	-22.5	
IDM	Pulsed Drain Current ①	-142	
PD @ TC = 25°C	Max. Power Dissipation	300	W
	Linear Derating Factor	2.4	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	320	mJ
IAR	Avalanche Current ①	-35.5	A
EAR	Repetitive Avalanche Energy ①	30	mJ
dv/dt	Peak Diode Recovery dv/dt ③	10	V/ns
TJ	Operating Junction	-55 to 150	°C
TSTG	Storage Temperature Range		
	Pckg. Mounting Surface Temp.	300 (for 5s)	
	Weight	3.3 (Typical)	g

For footnotes refer to the last page

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-200	—	—	V	$V_{GS} = 0V, I_D = -1.0mA$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.25	—	V/°C	Reference to $25^\circ\text{C}, I_D = -1.0mA$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.11	Ω	$V_{GS} = -12V, I_D = -35.5A$ ④
		—	—	0.102		$V_{GS} = -12V, I_D = -22.5A$
		—	—	0.2		$V_{GS} = -12V, I_D = -22.5A, T_J = 125^\circ\text{C}$
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS} = V_{GS}, I_D = -1mA$
g_{fs}	Forward Transconductance	23	—	—	S	$V_{DS} > -15V, I_D = -22.5A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	-10	μA	$V_{DS} = -200V, V_{GS} = 0V$
		—	—	-25		$V_{DS} = -160V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS} = -20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS} = 20V$
Q_g	Total Gate Charge	—	—	180	nC	$I_D = -35.5A$
Q_{gs}	Gate-to-Source Charge	—	—	60		$V_{DS} = -100V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	40		$V_{GS} = -12V$
$t_{d(on)}$	Turn-On Delay Time	—	—	35	ns	$V_{DD} = -100V, I_D = -35.5A$
t_r	Rise Time	—	—	80		$V_{GS} = -12V, R_G = 2.35\Omega$
$t_{d(off)}$	Turn-Off Delay Time	—	—	100		
t_f	Fall Time	—	—	200		
$LS + LD$	Total Inductance	—	4.0	—	nH	Measured from the center of drain pad to center of source pad
C_{iss}	Input Capacitance	—	7170	—	pF	$V_{GS} = 0V, V_{DS} = -25V$
C_{oss}	Output Capacitance	—	920	—		$f = 1.0MHz$
C_{rss}	Reverse Transfer Capacitance	—	86	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-35.5	A	
I_{SM}	Pulse Source Current (Body Diode) ①	—	—	-142		
V_{SD}	Diode Forward Voltage	—	—	-5.0	V	$T_J = 25^\circ\text{C}, I_S = -35.5A, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	—	450	ns	$T_J = 25^\circ\text{C}, I_F = -35.5A, di/dt \leq -100A/\mu\text{s}$
Q_{RR}	Reverse Recovery Charge	—	—	5.5	μC	$V_{DD} \leq -50V$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $LS + LD$.				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	0.42	°C/W	
$R_{thJ-PCB}$	Junction-to-PC board	—	1.6	—		soldered to a 2" square copper-clad board

Note: Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

Radiation Characteristics

IRHNA597260

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

	Parameter	100KRads(Si) ¹		300KRads(Si) ²		Units	Test Conditions
		Min	Max	Min	Max		
BV _{DSS}	Drain-to-Source Breakdown Voltage	-200	—	-200	—	V	V _{GS} = 0V, I _D = -1.0mA
V _{GS(th)}	Gate Threshold Voltage	-2.0	-4.0	-2.0	-5.0		V _{GS} = V _{DS} , I _D = -1.0mA
I _{GSS}	Gate-to-Source Leakage Forward	—	-100	—	-100	nA	V _{GS} = -20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	100	—	100		V _{GS} = 20 V
I _{DSS}	Zero Gate Voltage Drain Current	—	-10	—	-10	μA	V _{DS} = -160V, V _{GS} = 0V
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.103	—	0.103	Ω	V _{GS} = -12V, I _D = -22.5A
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (SMD-2)	—	0.102	—	0.102	Ω	V _{GS} = -12V, I _D = -22.5A
V _{SD}	Diode Forward Voltage ④	—	-5.0	—	-5.0	V	V _{GS} = 0V, I _S = -35.5A

1. Part number IRHNA597260,

2. Part number IRHNA593260

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Single Event Effect Safe Operating Area

Ion	LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)				
				@ VGS=0V	@ VGS=5V	@ VGS=10V	@ VGS=15V	@ VGS=20V
Br	37.3	285	36.8	- 200	- 200	- 200	- 200	-75
I	59.9	345	32.7	- 200	- 200	- 200	- 50	—
Au	82.3	357	28.5	- 200	- 200	- 200	- 35	—

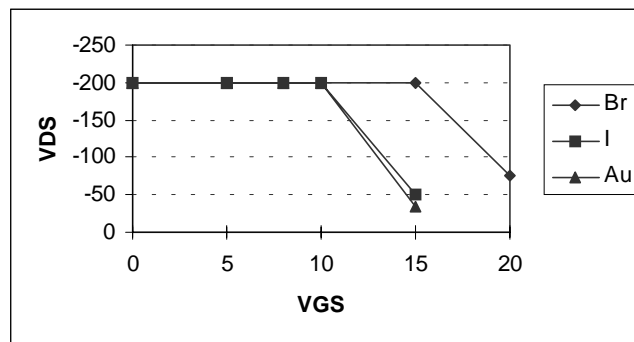


Fig a. Single Event Effect, Safe Operating Area

For footnotes refer to the last page

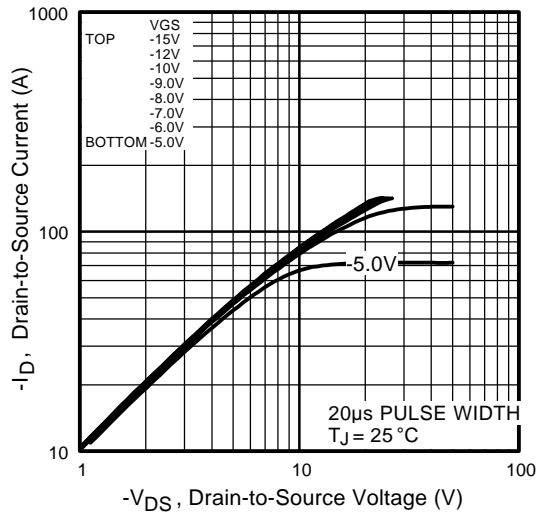


Fig 1. Typical Output Characteristics

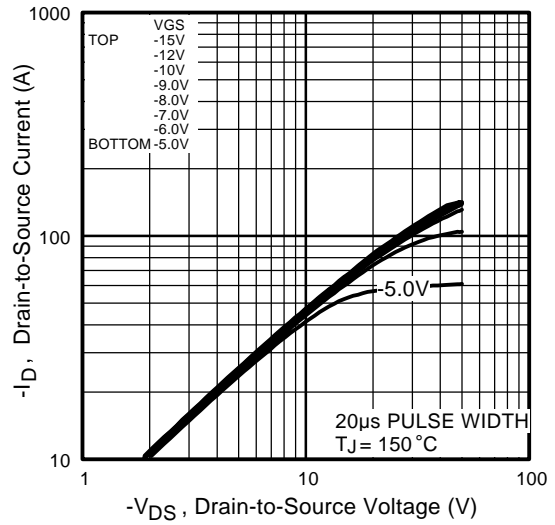


Fig 2. Typical Output Characteristics

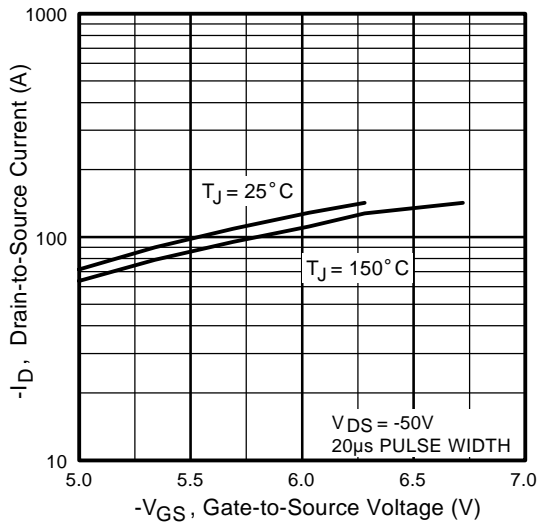


Fig 3. Typical Transfer Characteristics

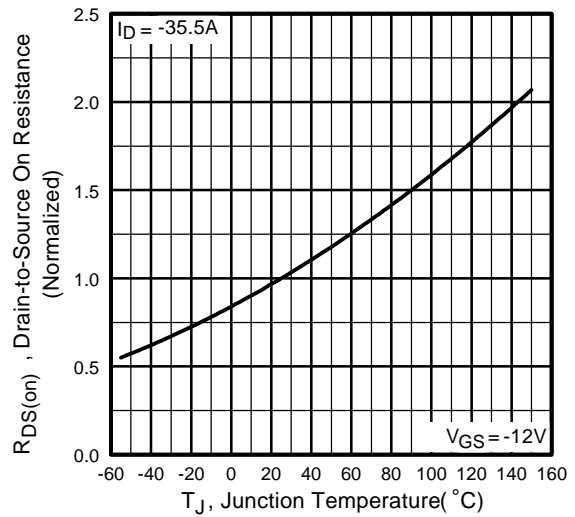


Fig 4. Normalized On-Resistance Vs. Temperature

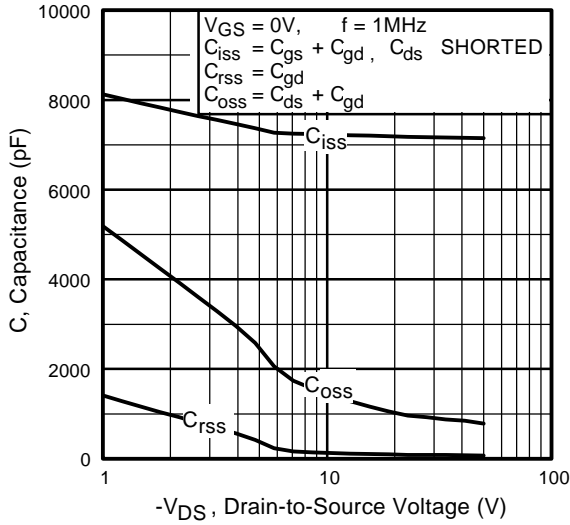


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

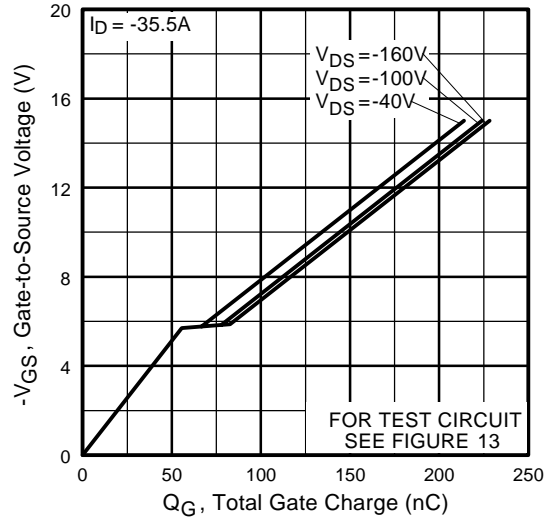


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

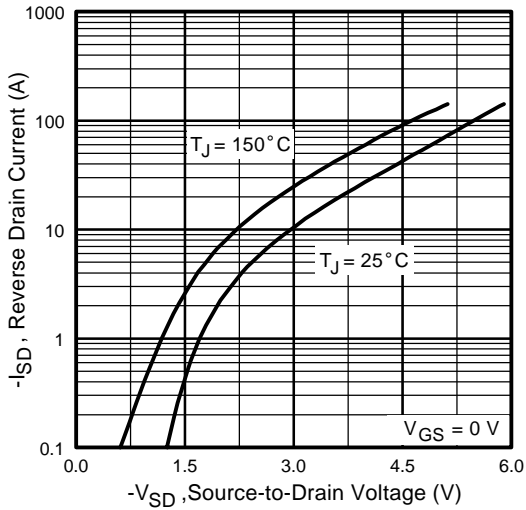


Fig 7. Typical Source-Drain Diode Forward Voltage

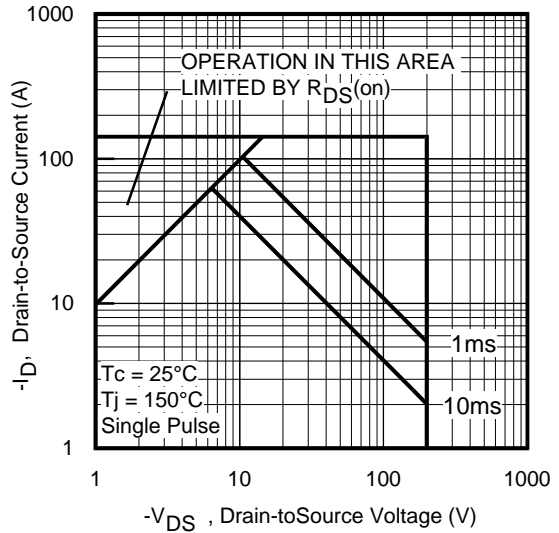


Fig 8. Maximum Safe Operating Area

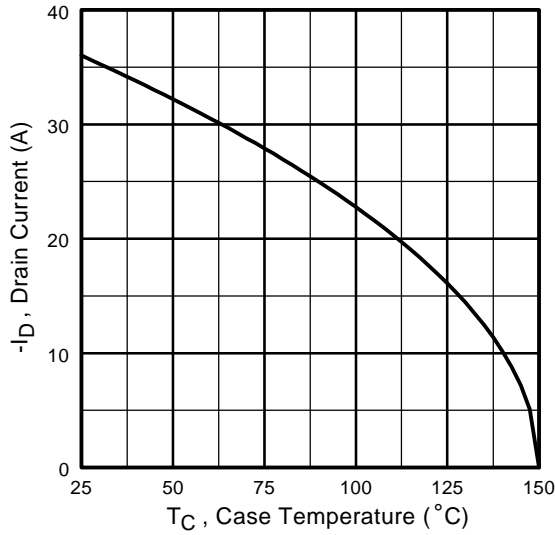


Fig 9. Maximum Drain Current Vs. Case Temperature

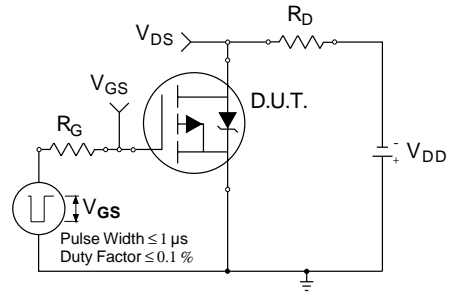


Fig 10a. Switching Time Test Circuit

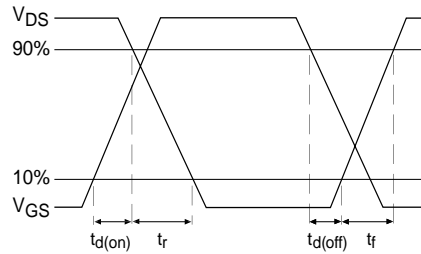


Fig 10b. Switching Time Waveforms

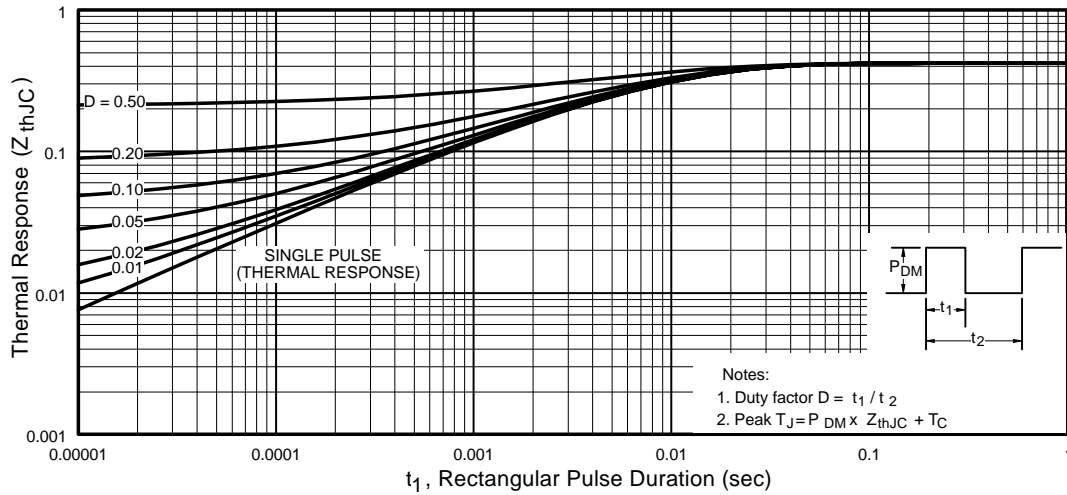


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

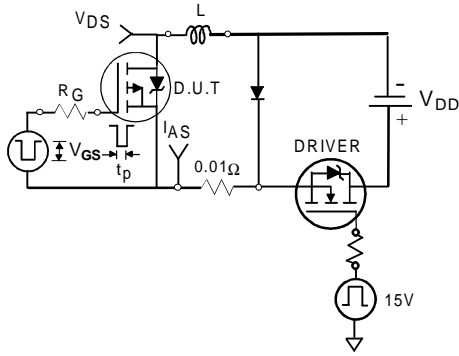


Fig 12a. Unclamped Inductive Test Circuit

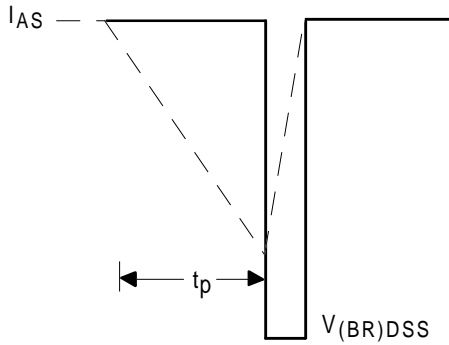


Fig 12b. Unclamped Inductive Waveforms

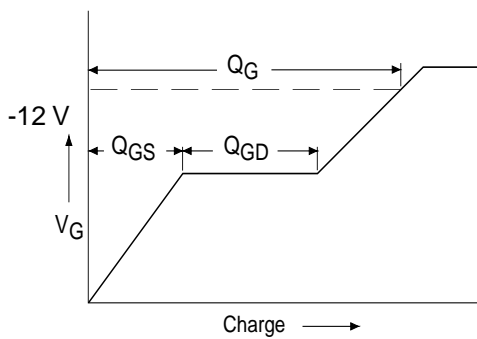


Fig 13a. Basic Gate Charge Waveform

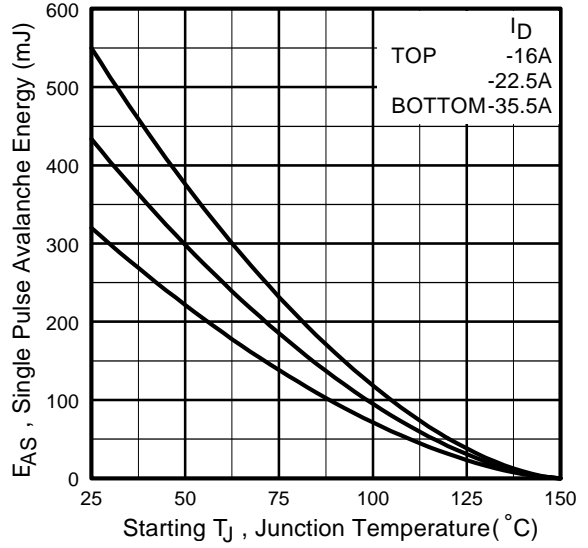


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

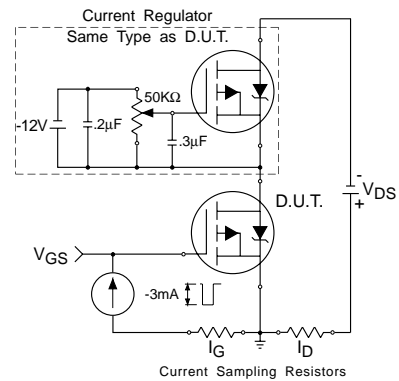
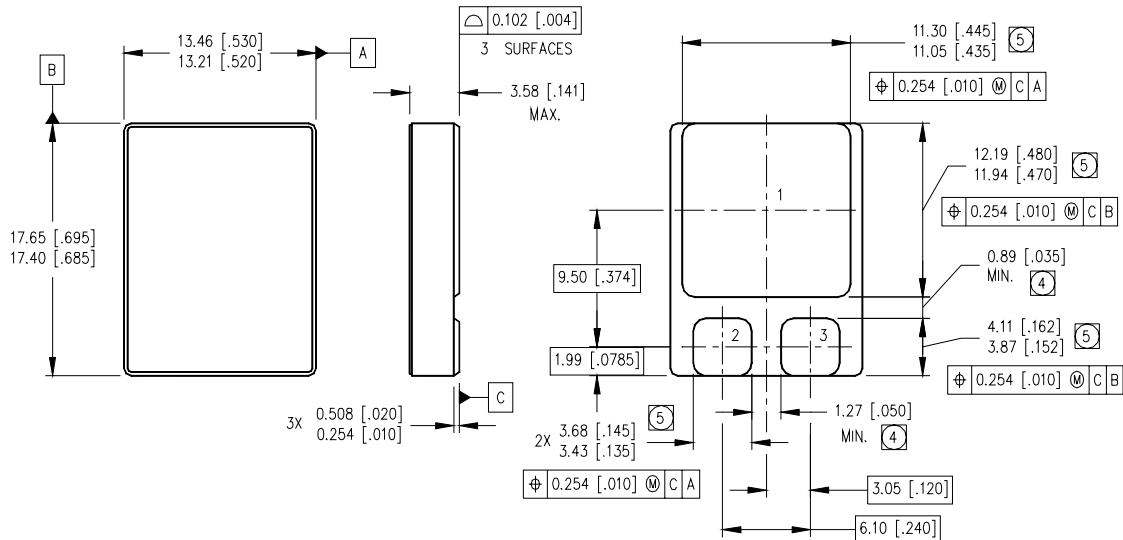


Fig 13b. Gate Charge Test Circuit

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② $V_{DD} = -50V$, starting $T_J = 25^\circ C$, $L=0.5\text{ mH}$
Peak $I_L = -35.5A$, $V_{GS} = -12V$
- ③ $I_{SD} \leq -35.5A$, $di/dt \leq -450A/\mu s$,
 $V_{DD} \leq -200V$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300\ \mu s$; Duty Cycle $\leq 2\%$
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
-12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
-160 volt V_{DS} applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — SMD-2



NOTES:

- 1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- ④ DIMENSION INCLUDES METALLIZATION FLASH.
- ⑤ DIMENSION DOES NOT INCLUDE METALLIZATION FLASH.

PAD ASSIGNMENTS

- 1 = DRAIN
- 2 = GATE
- 3 = SOURCE



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